

ABSTRACT OF THE DISCLOSURE

Process solutions comprising one or more surfactants are used to reduce the
5 number of defects in the manufacture of semiconductor devices. In certain preferred
embodiments, the process solution of the present invention may reduce defects when
employed as a rinse solution either during or after the development of the CMP
processing. Also disclosed is a method for reducing the number of defects on a plurality
of post-CMP processed substrates employing the process solution of the present
10 invention.